# imall

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# RFM products are now Murata products.

SF2143B

72.54 / 80.46 MHz

**SAW Diplexer** 

## Designed for SDARS IF

- SAW Diplexer 72.54 MHz / 80.46 MHz
- 5.0 X 7.0 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)

## Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any Two Terminals	0	VDC
Operating Temperature Range	-40 to +105	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Peak Solder Reflow Temperature, 10 seconds/5 cycles	260	°C



## **Electrical Characteristics TDM1 Filter**

Characteristic		Sym	Notes	Min	Тур	Max	Units	
Nominal Center Frequency		f <sub>C</sub>		72.54			MHz	
Passband Width:	1 dB	BW <sub>1</sub>	1	3.7	4.1		MHz	
	15 dB	BW <sub>15</sub>	'		6.4	6.7	MHz	
	30 dB	BW <sub>30</sub>			7.3	7.5	MHz	
Passband Minimum Insertion Loss (including matching	network) at f <sub>C</sub>	IL <sub>MIN</sub>			16	18	dB	
Amplitude Ripple, f <sub>C</sub> ± 1.85 MHz					0.6	1.3	dB <sub>P-P</sub>	
Attenuation Relative to Minimum Insertion Loss:	50.00 to 66.48 MHz			40	42		dB	
	66.48 to 68.08 MHz			37	42		dB	
	77.30 to 78.60 MHz			30	33		dB	
	78.60 to 86.50 MHz			30	33		dB	
	86.50 to 91.50 MHz			39	43		dB	
	91.50 to 100.0 MHz			42	46		dB	
Group Delay Ripple					30	150	ns <sub>P-P</sub>	
Source Impedance, Differential				27	ohms or 200 oh	ms		
Load Impedance, Differential				1K ohms or 1.5K ohms				

### **Electrical Characteristics TDM2 Filter**

Characteristic		Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency		f <sub>C</sub>		80.46			MHz
Passband Width:	1 dB	BW <sub>1</sub>	1	3.7	4.2		MHz
	15 dB	BW <sub>15</sub>			6.4	6.7	MHz
	30 dB	BW <sub>30</sub>			7.2	7.5	MHz
Passband Minimum Insertion Loss (including the match	ing network) at f <sub>C</sub>	IL <sub>MIN</sub>			15	18	dB
Amplitude Ripple, f <sub>C</sub> ± 1.85 MHz					0.7	1.3	dB <sub>P-P</sub>
Attenuation Relative to Minimum Insertion Loss:	50.00 to 74.39 MHz			39	42		dB
	74.39 to 75.99 MHz			33	38		dB
	85.21 to 86.50 MHz			30	38		dB
	86.50 to 91.50 MHz			35	40		dB
	91.50 to 100.0 MHz			43	46		dB
Group Delay Ripple					40	150	ns <sub>P-P</sub>
Source Impedance, Differential				27 ohms or 200 ohms			
Load Impedance, Differential				1K ohms or 1.5K ohms			
Case Style			6	SMP		SMP-03 7 x 5 mm Nominal Footpri	
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			0		RFM SF21	43B YYWWS	

### CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

#### Ŷ NOTES:

Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50  $\Omega$  and measured with 50  $\Omega$  network analyzer. 1.

2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.

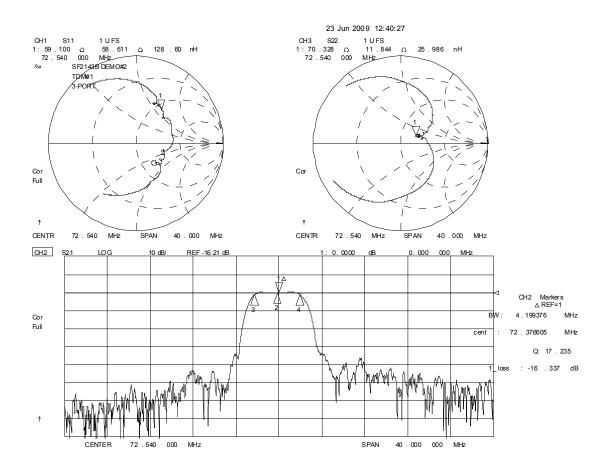
4.

The design, manufacturing process, and specifications of this filter are subject to change. Tape and Reel Standard ANSI / EIA 481. 5. 6.

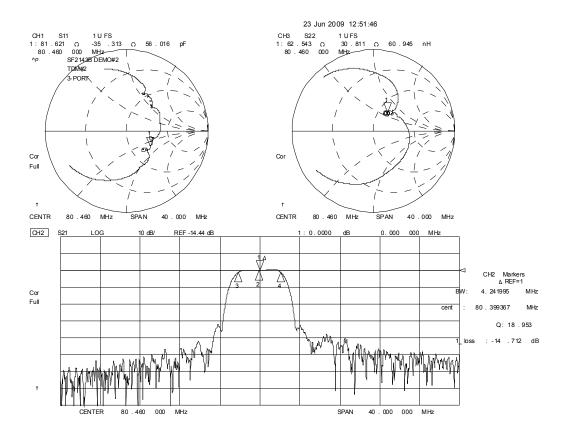
Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design. US and international patents may apply. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd. 7. 8

Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes." 3.

**TDM1 Amplitude and Impedance Plots** 

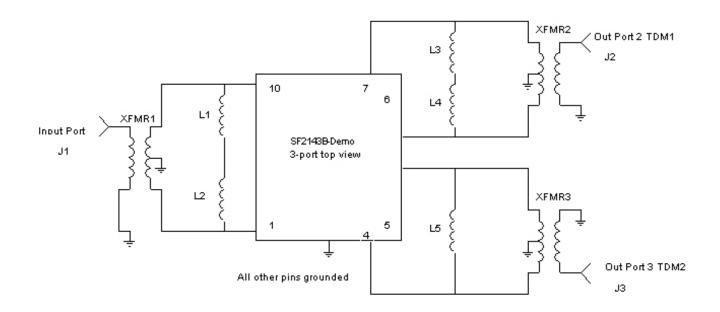


**TDM2** Amplitude and Impedance Plots



# **Test Circuit**

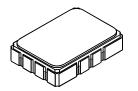
SF2143B Demo Board



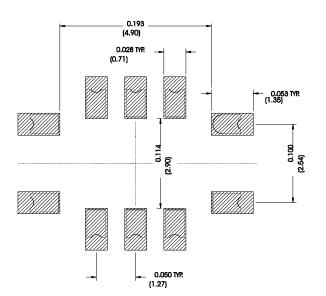
J1-J3	500-0248-002 4 hole flange SMA connector			
PCB	400-1768-001 Gold 7 × 5 mm pkg PCB			
XFMR2, XFMR3	501-0912-004 16:1 Transformer			
XFMR1	501-0912-001 4:1 Transformer			
L1	501-0782-101 100nH 0805 Ind			
L2	501-0782-270 27nH 0805 Ind			
L3	501-0782-390 390nH 0805 Ind			
L4	501-0782-120 12nH 0805 Ind			
L5	501-0782-331 330 nH 0805 Ind			

# SMP-03 Case

# 10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



# **Recommended PCB Footprint**

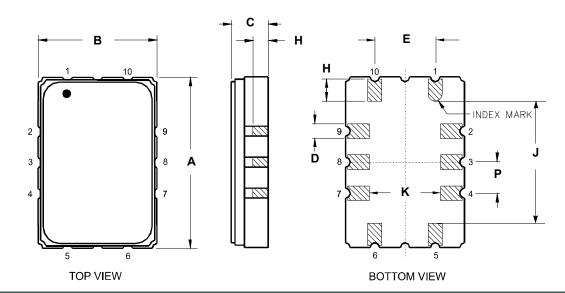


Dimension	mm		Inches			
Dimension	Min	Nom	Max	Min	Nom	Max
Α	6.80	7.00	7.20	0.268	0.276	0.283
В	4.80	5.00	5.20	0.189	0.197	0.205
С	-	1.65	2.00	-	0.065	0.079
D	0.47	0.60	0.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
Н	0.87	1.00	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
К	2.87	3.00	3.13	0.113	0.118	0.123
Р	1.14	1.27	1.40	0.045	0.050	0.055

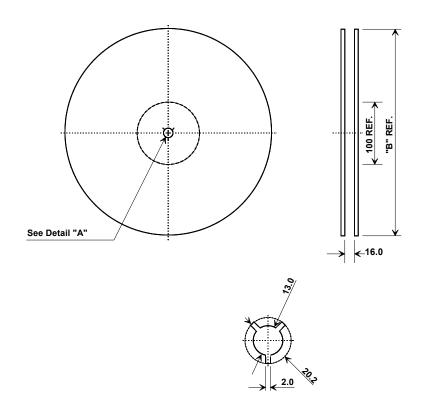
## **Electrical Connections**

**Case Dimensions** 

		Connection	Terminals			
Port 1	Input		1			
FULL	Input		10			
Port 2	Outpu	ut TDM1	6			
FULZ	Outpu	ut TDM1	7			
Port 3	Outpu	ut TDM2	4			
FULS	Outpu	ut TDM2	5			
	Grou	nd	All others			
	Materials					
Solder F Plating	Pad	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel				
Lid Plati	ng	2.0 to 3.0 µm Nickel				
Body		Al <sub>2</sub> O <sub>3</sub> Ceramic				
Pb Free						



# **Tape and Reel Specifications**



	"B"	Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

# **COMPONENT ORIENTATION and DIMENSIONS**

Carrier Tape Dimensions				
Ao	5.5 mm			
Во	7.5 mm			
Ко	2.0 mm			
Pitch	8.0 mm			
W	16.0 mm			

